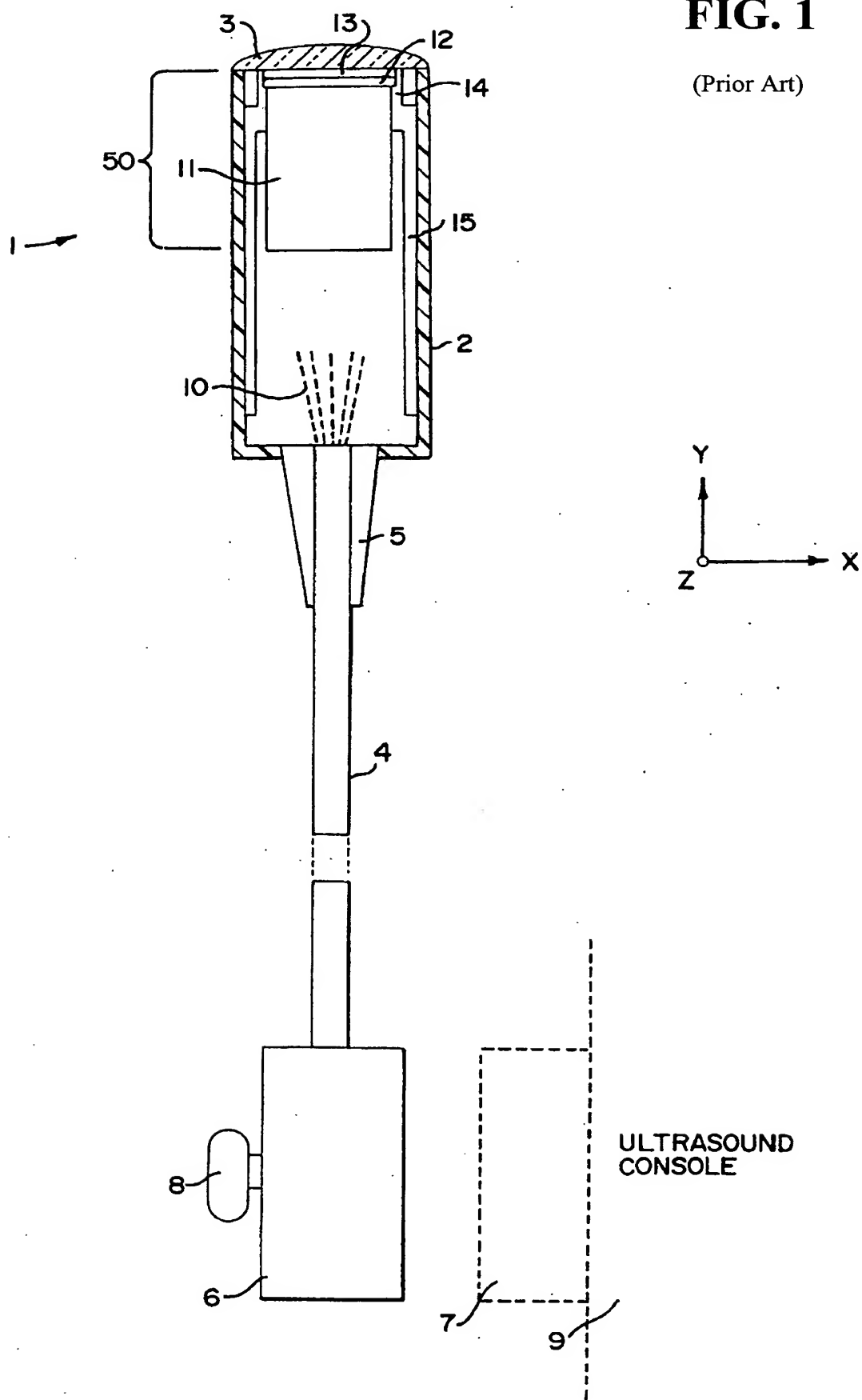


FIG. 1 (1/11)

(Prior Art)



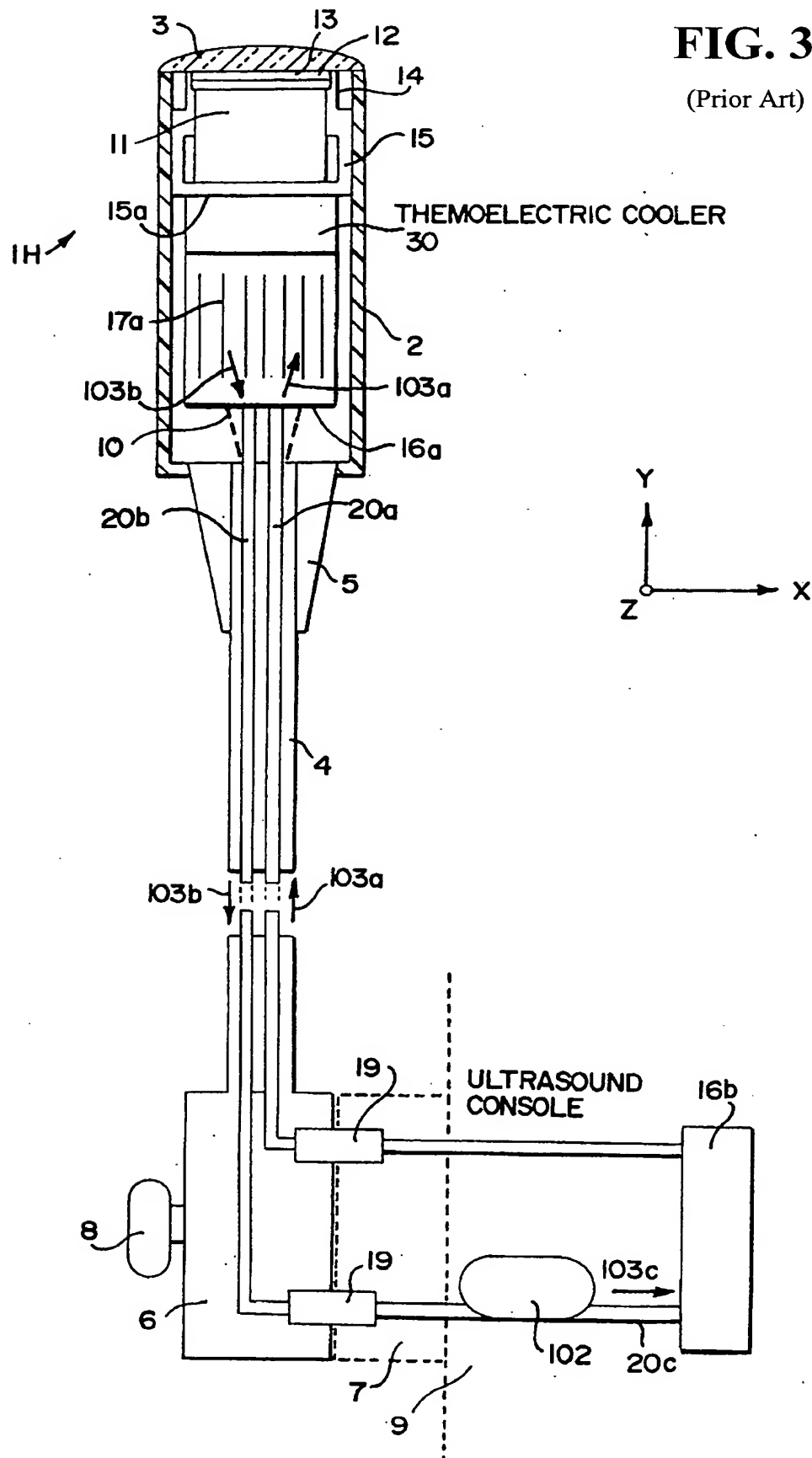
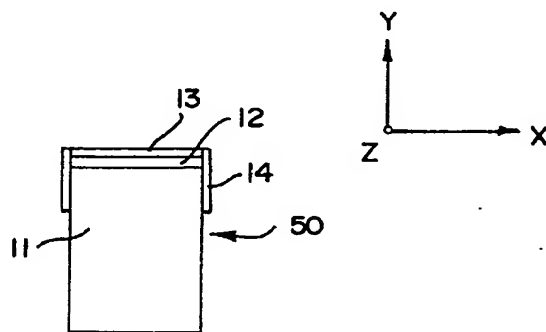


FIG. 2

(3/11)



100

FIG. 4

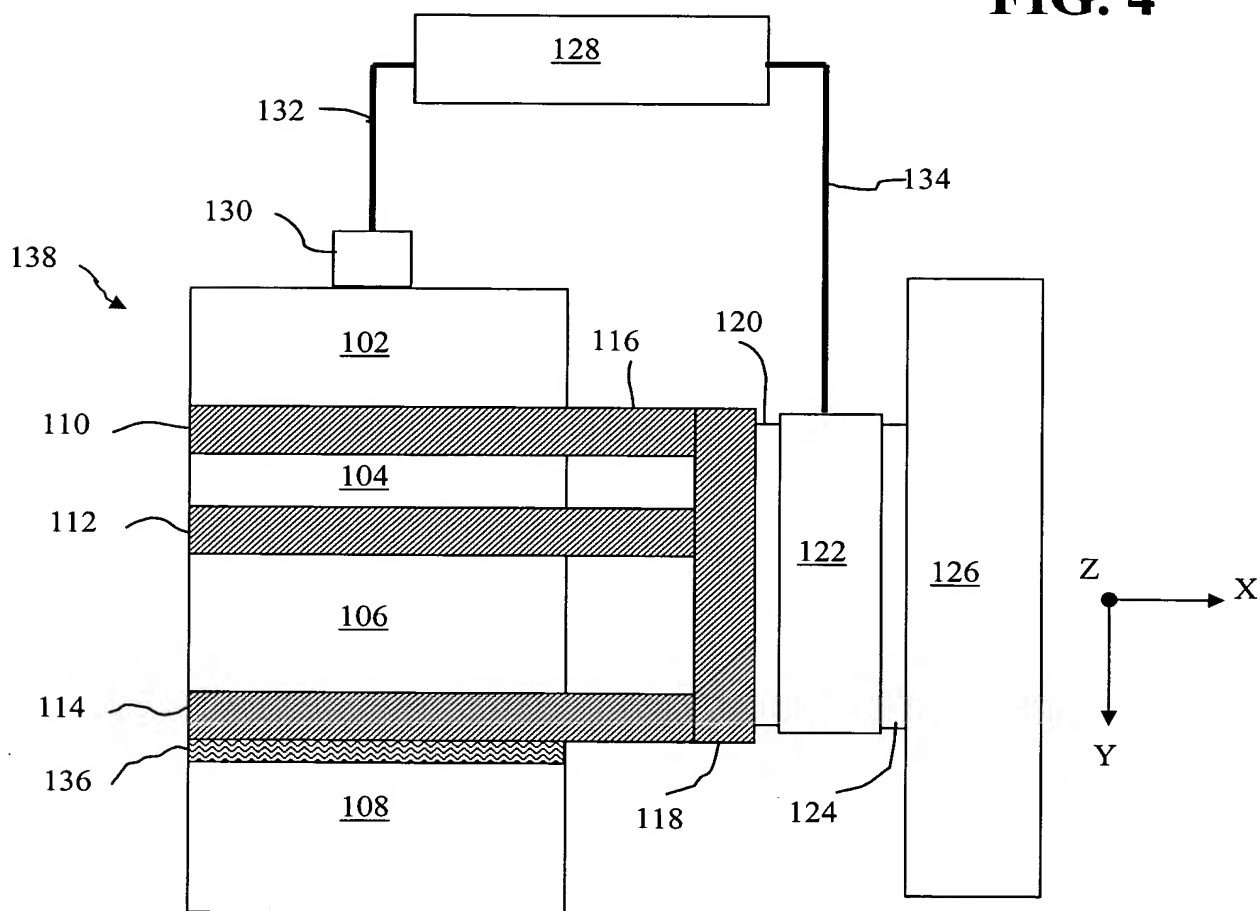


FIG. 5A

(4/11)

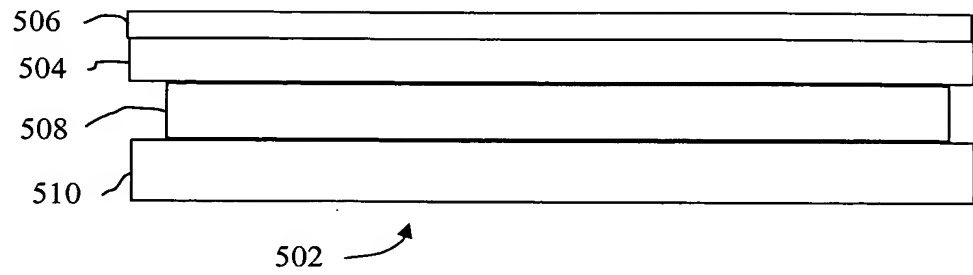


FIG. 5B

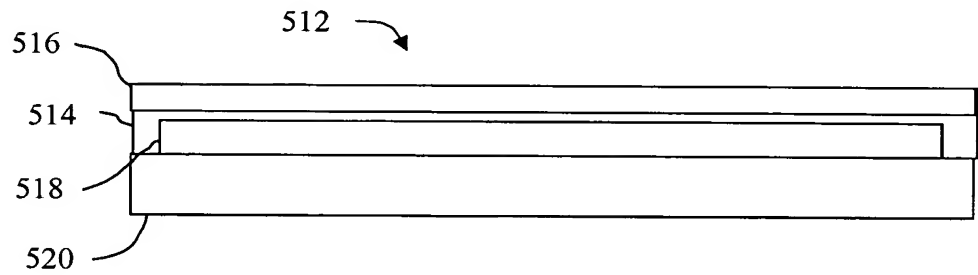
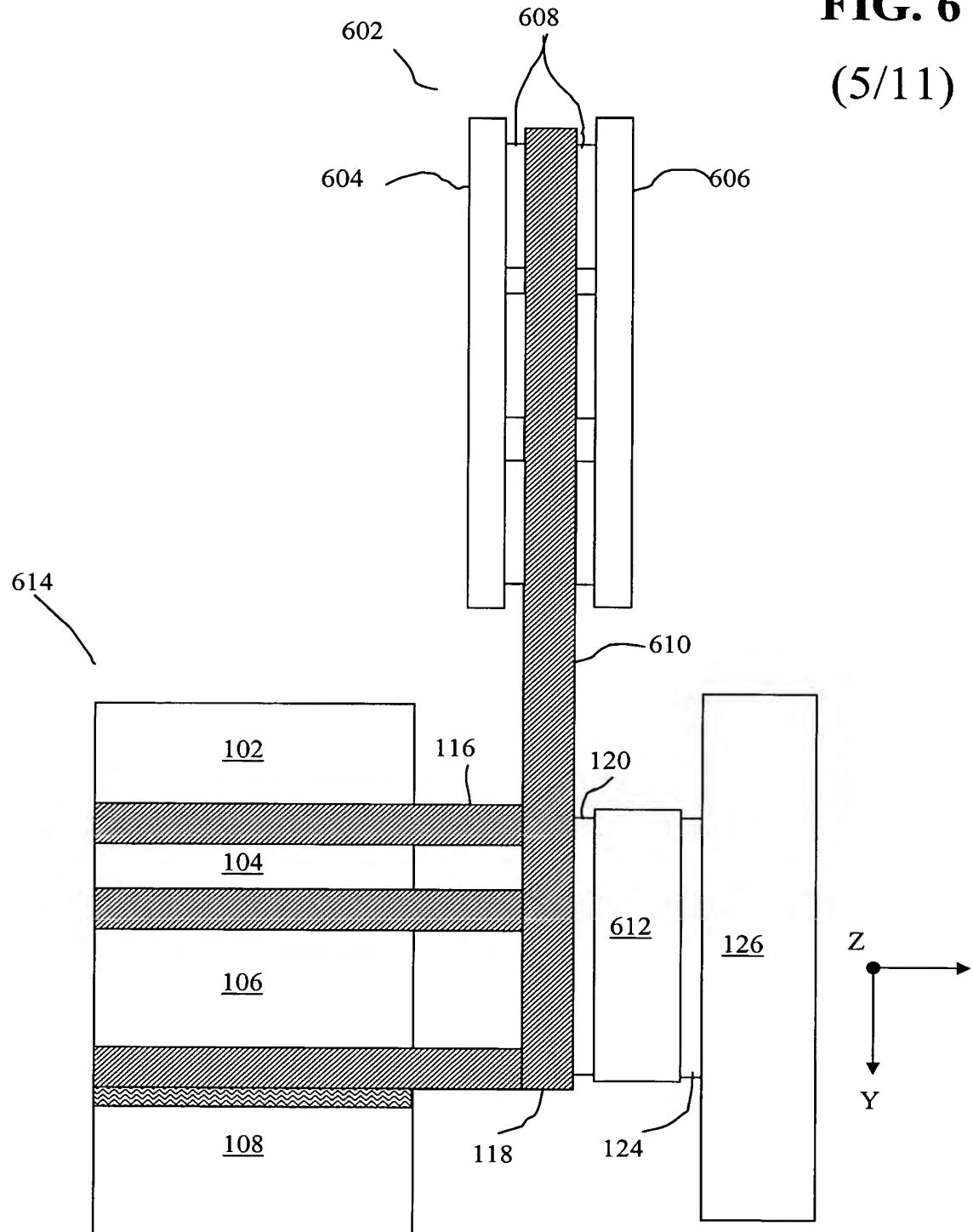


FIG. 6
(5/11)



ELECTRONICS SUBASSEMBLY
WITH HEAT GENERATING COMPONENTS

FIG. 7A

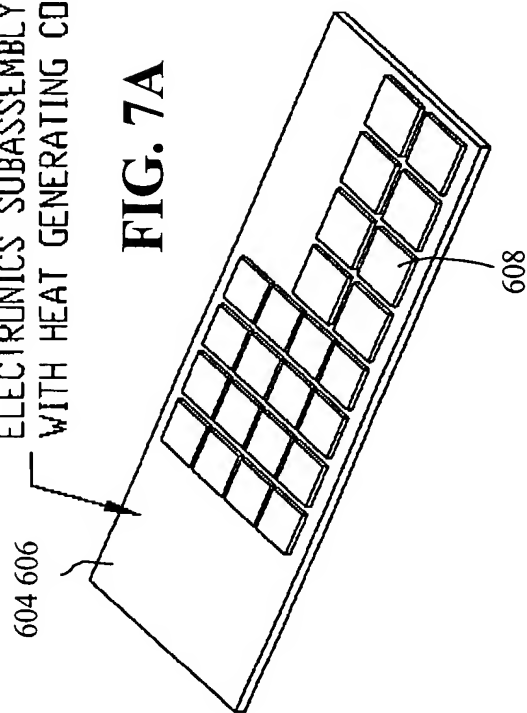


FIG. 7C

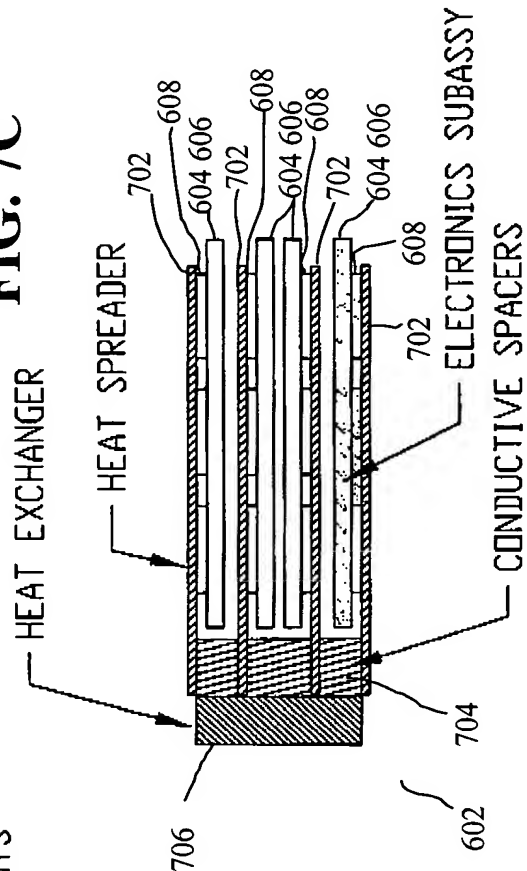


FIG. 7D

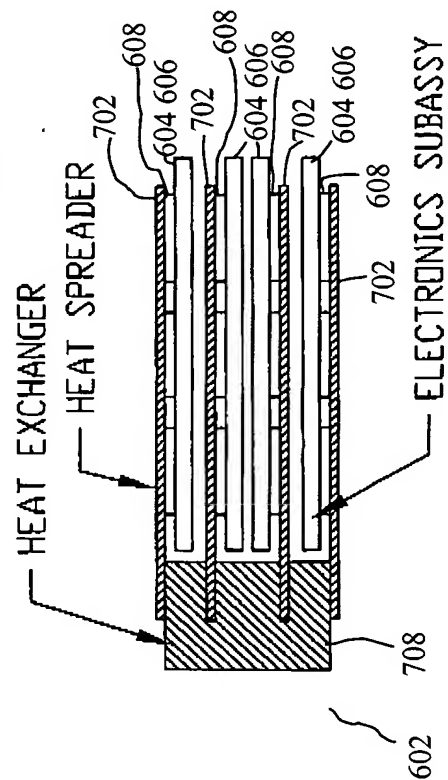
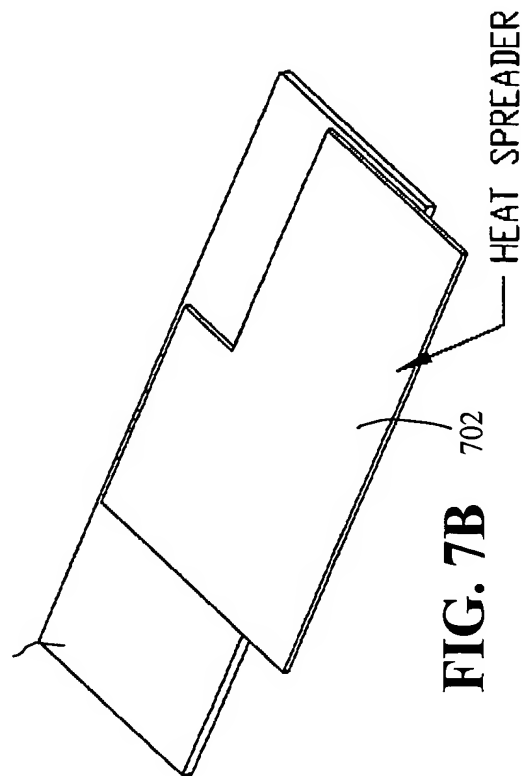


FIG. 7B



ELECTRONICS SUBASSY ON
THERMALLY ENHANCED PC BOARD

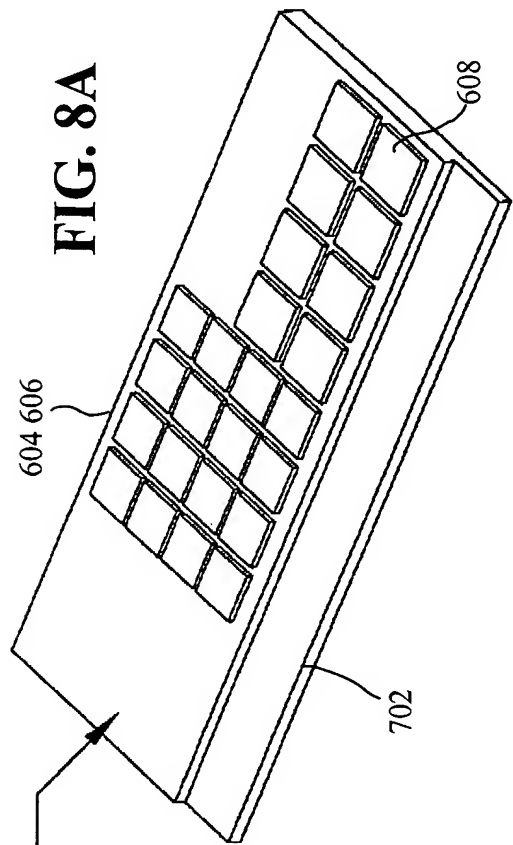


FIG. 8A

(7/11)

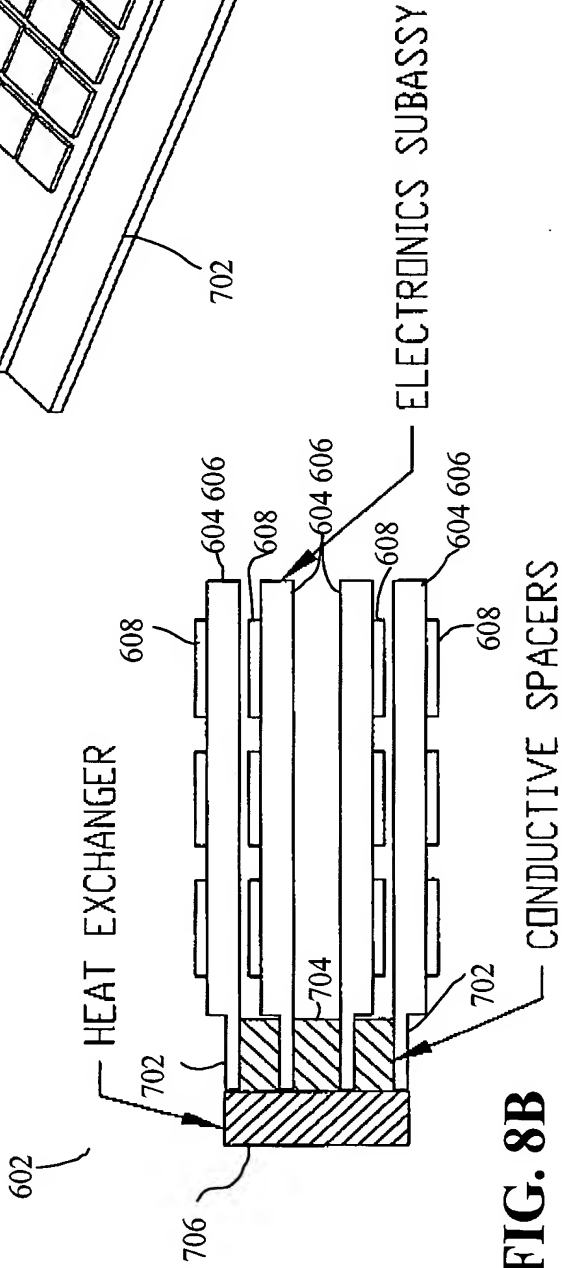


FIG. 8B

ELECTRONICS SUBASSY

HEAT PIPE

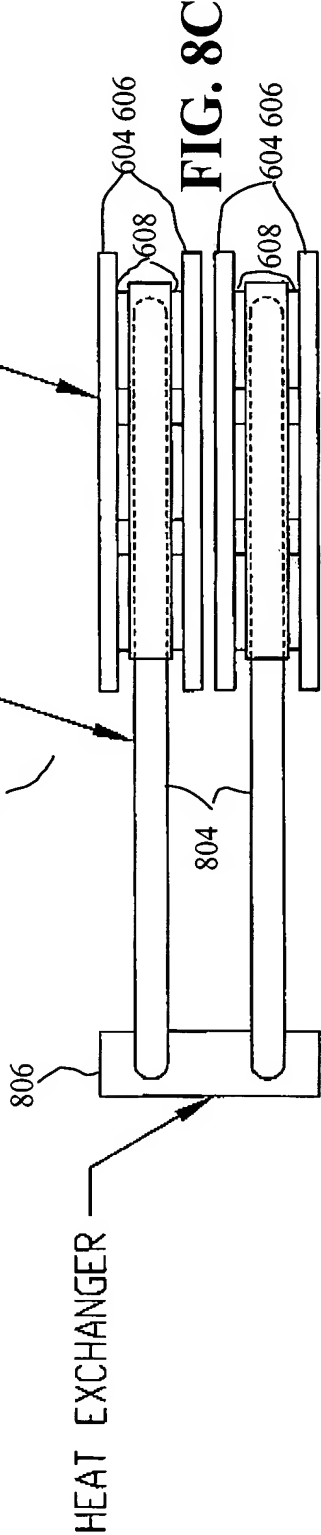


FIG. 8C

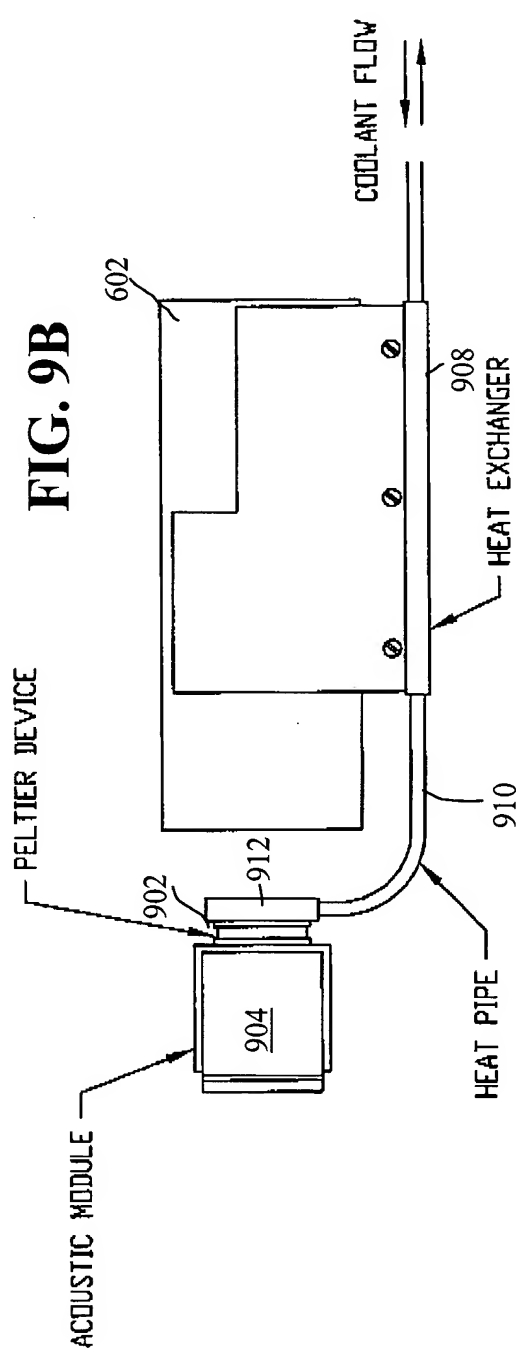
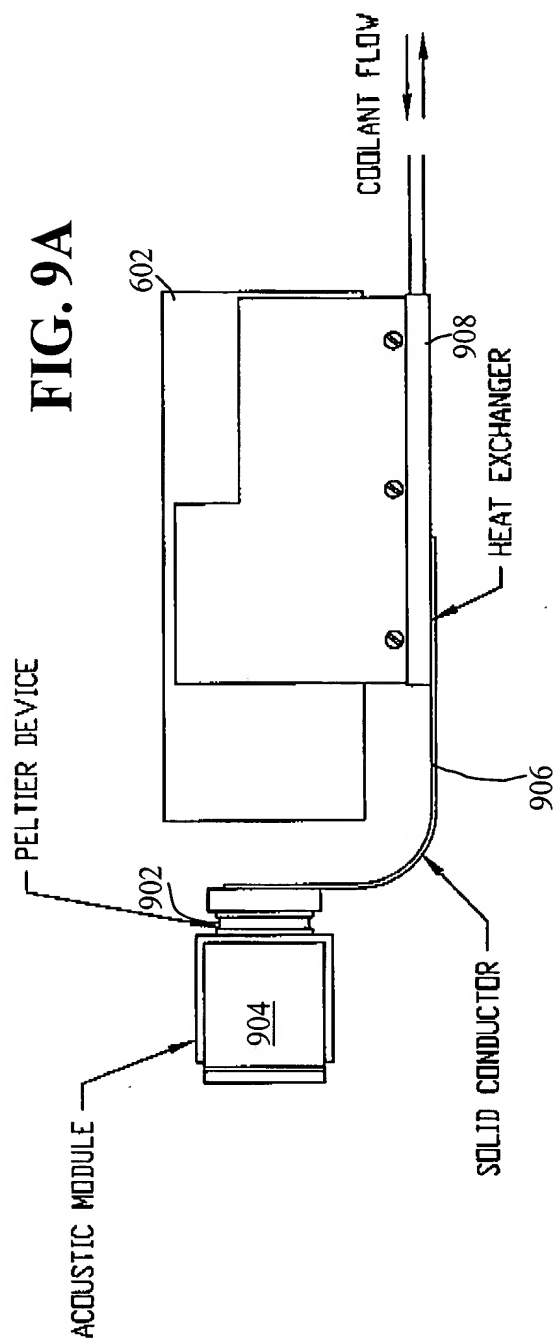


FIG. 9

(8/11)

